

67,200-506; TSMC 00-804  
Serial Number 09/920,911

#11  
Response  
5-29-03  
and J

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**TO:** Assistant Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**FAX RECEIVED**

**FROM:** Tung & Associates  
838 West Long Lake Road - Suite 120  
Bloomfield Hills, MI 48302

MAY 23 2003

TECHNOLOGY CENTER 2800

**DATE:** 16 May 2003

**REF:** Applicant : Yu et al. Filing Date : 2 August 2001  
Serial No : 09/920,911 Att'y No. : 67,200-506  
Art Unit : 2812 Examiner : Richard A. Booth  
Title : Thermal Compensation Method for Forming Semiconductor  
Integrated Circuit Microelectronic Fabrication

**RESPONSE TO OFFICE ACTION MADE FINAL**

Sir:

In response to an office action mailed on 26 March 2003 and made FINAL, please consider the following remarks directed towards the above referenced patent application.

There are no amendments to the specification, claims or the drawings. A listing of the claims begins on page 2 of this paper. Remarks begin on page 6 of this paper.

**CERTIFICATE OF FACSIMILE TRANSMISSION**

I hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office at facsimile number 703-872-9319, on May 23, 2003.

  
Kathy Dixon